

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT2894644

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	RELEASE OF SECURITY INTEREST	
<b>CONVEYING PARTY DATA</b>		
<b>Name</b>		<b>Execution Date</b>
CITIBANK, N.A., AS COLLATERAL AGENT		05/05/2014
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	FREESCALE SEMICONDUCTOR, INC.	
<b>Street Address:</b>	6501 WILLIAM CANNON DRIVE WEST	
<b>City:</b>	AUSTIN	
<b>State/Country:</b>	TEXAS	
<b>Postal Code:</b>	78735	
<b>PROPERTY NUMBERS Total: 7</b>		
<b>Property Type</b>	<b>Number</b>	
<b>Patent Number:</b>	7803714	
<b>Patent Number:</b>	7935571	
<b>Patent Number:</b>	8283207	
<b>Patent Number:</b>	8344503	
<b>Patent Number:</b>	8039386	
<b>Patent Number:</b>	7446017	
<b>Application Number:</b>	13731242	
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Email:</b>	kperricone@tessera.com	
<b>Correspondent Name:</b>	INVENSAS CORPORATION	
<b>Address Line 1:</b>	3025 ORCHARD PARKWAY	
<b>Address Line 2:</b>	ATTN: IP DEPT.	
<b>Address Line 4:</b>	SAN JOSE, CALIFORNIA 95134	
<b>ATTORNEY DOCKET NUMBER:</b>	FREESCALE RELEASE-COR	
<b>NAME OF SUBMITTER:</b>	CHRISTOPHER W. LATTIN	
<b>SIGNATURE:</b>	/Christopher W. Lattin/	
<b>DATE SIGNED:</b>	06/11/2014	
<b>Total Attachments: 4</b>		

PATENT

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## PATENT RELEASE

THIS RELEASE is effective as of May 5, 2014 by Citibank, N.A., as Collateral Agent (as defined below) for the Lenders. Capitalized terms used herein and not otherwise defined shall have the meanings assigned to such terms in the Credit Agreement and IP Agreement, in each case, referred to below.

A. Reference is made to (i) the THIRD AMENDED AND RESTATED CREDIT AGREEMENT entered into as of March 1, 2013 (as otherwise amended, supplemented or modified from time to time, the “**Credit Agreement**”), among FREESCALE SEMICONDUCTOR, INC. (the “**Borrower**”), a Delaware corporation, FREESCALE SEMICONDUCTOR HOLDINGS V, INC. (“**Holdings**”), a Delaware corporation, FREESCALE SEMICONDUCTOR HOLDINGS IV, LTD., a Bermuda exempted limited liability company, FREESCALE SEMICONDUCTOR HOLDINGS III, LTD. (“**Parent**”), a Bermuda exempted limited liability company, CITIBANK, N.A., as administrative agent, collateral agent (in such capacity, the “**Collateral Agent**”), swing line lender and L/C issuer, and each lender from time to time party thereto (collectively, the “**Lenders**”); (ii) the INTELLECTUAL PROPERTY SECURITY AGREEMENT (as amended, supplemented or modified from time to time, the “**IP Agreement**”) dated as of December 1, 2006, among the Borrower, Holdings, the Subsidiaries of Parent from time to time party thereto and CITIBANK, N.A., as Collateral Agent; (iii) the PATENT SECURITY AGREEMENT (as amended, supplemented or modified from time to time, “**March Patent Agreement**”) dated as of March 12, 2008, among the Borrower and CITIBANK, N.A., as Collateral Agent; (iv) the PATENT SECURITY AGREEMENT (as amended, supplemented or modified from time to time, “**July Patent Agreement**”) dated as of July 28, 2008, among the Borrower and CITIBANK, N.A., as Collateral Agent; (v) the SUPPLEMENT NO. 4 (the “**Supplement**”) dated as of June 5, 2008, to the IP Agreement, among the Borrower, Holdings, the Subsidiaries of Parent and CITIBANK, N.A., as Collateral Agent; (vi) the SECURITY AGREEMENT dated as of December 1, 2006 among Freescale Acquisition Corporation, Freescale Semiconductor, Inc., Freescale Acquisition Holdings Corp., Freescale Holdings (Bermuda) IV, Ltd., the Subsidiaries of Freescale Holdings (Bermuda) III, Ltd. from time to time party thereto and Citibank, N.A. as Collateral Agent; and (vii) the other Collateral Documents (as defined in the Credit Agreement).

B. The IP Agreement was recorded in the Patent Division of the United States Patent and Trademark Office on February 2, 2007, at Reel 018855 and Frame 0129. The Supplement was recorded in the Patent Division of the United States Patent and Trademark Office on July 9, 2008, at Reel 021212 and Frame 0372. The March Patent Agreement was recorded in the Patent Division of the United States Patent and Trademark Office on July 11, 2008, at Reel 021217 and Frame 0368. The July Patent Agreement was recorded in the Patent Division of the United States Patent and Trademark Office on September 24, 2008, at Reel 021570 and Frame 0449.

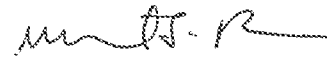
C. The Borrower has informed the Collateral Agent that it has disposed of the Patents listed on Schedule I attached hereto in a transaction permitted under the Credit Agreement.

Accordingly, the Collateral Agent's interest (including security interests) in and to the Patents listed on Schedule I attached hereto shall hereby terminate and the security interest recorded with the United States Patent & Trademark Office against such Patents shall hereby cease and become void.

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IN WITNESS WHEREOF, the Collateral Agent has caused this Release to be duly executed by its duly authorized officer.

CITIBANK, N.A., as Collateral Agent,

Signature: 

Print: Matthew Burke

Title: Vice President

Date: May 5, 2014

[Patent Release]

## **SCHEDULE I**

### **I. Patents**

<b>Holder</b>	<b>Patent No.</b>	<b>Description/Title</b>
FREESCALE SEMICONDUCTOR, INC.	7803714	SEMICONDUCTOR THROUGH SILICON VIAS OF VARIABLE SIZE AND METHOD OF FORMATION
FREESCALE SEMICONDUCTOR, INC.	7935571	THROUGH SUBSTRATE VIAS FOR BACK-SIDE INTERCONNECTIONS ON VERY THIN SEMICONDUCTOR WAFERS
FREESCALE SEMICONDUCTOR, INC.	8283207	METHODS OF FORMING THROUGH-SUBSTRATE CONDUCTOR FILLED VIAS, AND ELECTRONIC ASSEMBLIES FORMED USING SUCH METHODS
FREESCALE SEMICONDUCTOR, INC.	8344503	3-D CIRCUITS WITH INTEGRATED PASSIVE DEVICES
FREESCALE SEMICONDUCTOR, INC.	8039386	METHOD FOR FORMING A THROUGH SILICON VIA (TSV)
FREESCALE SEMICONDUCTOR, INC.	7446017	METHODS AND APPARATUS FOR RF SHIELDING IN VERTICALLY-INTEGRATED SEMICONDUCTOR DEVICES

### **II. Patent Applications**

<b>Holder</b>	<b>Application No.</b>	<b>Description/Title</b>
FREESCALE SEMICONDUCTOR, INC.	13/731242	METHODS OF FORMING 3-D CIRCUITS WITH INTEGRATED PASSIVE DEVICES